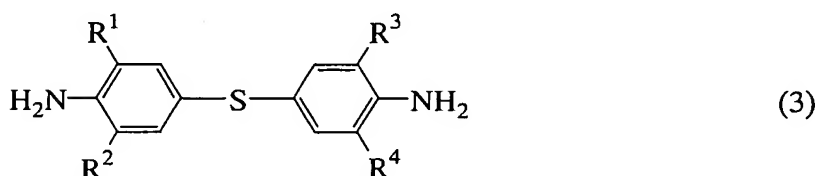
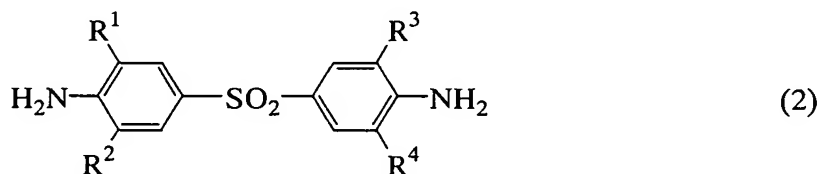
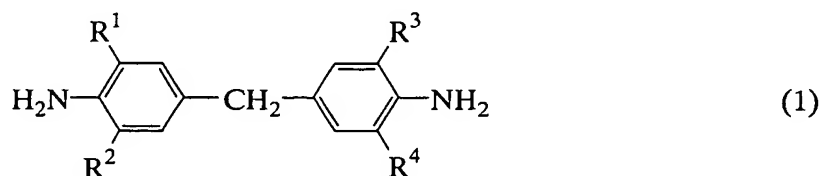


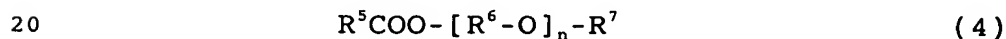
1. A liquid epoxy resin composition comprising

1. A liquid epoxy resin composition comprising
(A) a liquid epoxy resin,
5 (B) an aromatic amine curing agent comprising at least
5% by weight of at least one aromatic amine compound having a
purity of at least 99% selected from compounds having the
following general formulae (1) to (3):



- 10 wherein each of R¹ to R⁴ is hydrogen or a monovalent hydrocarbon group having 1 to 6 carbon atoms,
(C) an inorganic filler, and
(D) an ester organic solvent having a boiling point of 130 to 250°C in an amount of 0.5 to 10 parts by weight per
15 100 parts by weight of components (A) and (B) combined.

2. The composition of claim 1 wherein the ester organic solvent (D) has the general formula (4):



wherein R⁵ and R⁷ each are a monovalent hydrocarbon group having 1 to 6 carbon atoms, R⁶ is an alkylene group having 1 to 6 carbon atoms, and n is an integer of 0 to 3.

3. The composition of claim 1 wherein the liquid epoxy resin (A) and the aromatic amine curing agent (B) are present in a molar ratio (A)/(B) from 0.7/1 to 0.9/1, and the composition has a toughness K_{1c} of at least 3.5.

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4. The composition of claim 1, further comprising a silicone-modified resin in the form of a copolymer which is obtained from an alkenyl group-containing epoxy resin or phenolic resin and an organopolysiloxane having the average
10 compositional formula (5):



wherein R^8 is a substituted or unsubstituted monovalent
15 hydrocarbon group, "a" is a number of 0.01 to 0.1, "b" is a number of 1.8 to 2.2, and $1.81 \leq a+b \leq 2.3$, said organopolysiloxane containing per molecule 20 to 400 silicon atoms and 1 to 5 hydrogen atoms each directly attached to a silicon atom (i.e., SiH groups), by effecting addition of SiH
20 groups to alkenyl groups.

5. A semiconductor device which is encapsulated with the liquid epoxy resin composition of claim 1 in the cured state.

25 6. A flip chip type semiconductor device which is encapsulated with the liquid epoxy resin composition of claim 1 in the cured state as an underfill.